



IEEE CPMT



International Symposium and Exhibition on

Advanced Packaging Materials Processes, Properties and Interfaces

March 15-17, 2006
Georgia Tech Hotel and Conference Center
800 Spring Street NW
Atlanta, GA 30308

www.me.gatech.edu/APM06-IEEE/

Abstract Deadline: January 31, 2006

The symposium is devoted to advances made in electronic packaging materials. Topics of presentations will include, but are not limited to, lead-free, Cu low-k, thermal interface materials, 3D packaging, adhesion, underfills, encapsulants and coatings, bumping and solders, substrates including HDI, high thermal and dielectrics, reliability, nano-functional and passive materials.

To register, please go to: www.me.gatech.edu/APM06-IEEE/

Featuring Keynote Speakers

Dr. Masuo Mizuno

Chief R&D Officer

Sumitomo Bakelite Co., LTD., Japan.

Professor Herb Reichl

Director of Fraunhofer IZM and Head of the Research Center for Microperipheric Technologies-System Integration, Technical University of Berlin, Germany.

Dr. Ho-Ming Tong

Corporate Vice President and General Manager of Corporate R&D, ASE Group, Taiwan.

Professor Rao Tummala

Pettit Chair Professor in Microsystems Packaging and Director NSF-ERC in SOP Technology, Georgia Institute of Technology, USA.

Professional Development Workshop

A half-day workshop on Packaging Materials and Reliability will be given by Professors C.P. Wong and Jianmin Qu. The workshop is free to registered attendees.

Conference Proceedings

A Conference Proceedings will be published. To be included in the proceedings, a full paper (4 pages) must be received by Jan. 31, 2006.

Local Attractions

World of Coca-Cola at Atlanta: <http://www.woccatlanta.com/>

CNN Studio Tour: <http://www.cnn.com/StudioTour/>

The Largest Aquarium in the World: <http://www.georgiaaquarium.org/>